

SN74LVC1G11-EP

SCES787-JULY 2009

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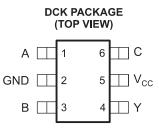
SINGLE 3-INPUT POSITIVE AND GATE

FEATURES

- Available in the Texas Instruments NanoFree[™] Package
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{nd} of 5.9 ns at 3.3 V
- Low Power Consumption, 10-µA Max Icc
- ±24-mA Output Drive at 3.3 V
- Ioff Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- **Controlled Baseline**
- **One Assembly/Test Site** .
- **One Fabrication Site**
- Available in Military (-55°C/125°C) Temperature Range⁽¹⁾
- Extended Product Life Cycle
- **Extended Product-Change Notification** •
- **Product Traceability**
- (1) Additional temperature ranges are available contact factory



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

The SN74LVC1G11 performs the Boolean function $Y = A \bullet B \bullet C$ or $Y = \overline{\overline{A} + \overline{B} + \overline{C}}$ in positive logic.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING		
–55°C to 125°C	SOT (SC-70) – DCK	Reel of 3000	SN74LVC1G11DCKREP	OBF		

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



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FUNCTION TABLE

	INPUTS	OUTPUT	
Α	В	С	Y
Н	Н	Н	Н
L	Х	Х	L
х	L	х	L
Х	Х	L	L

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedation	ance or power-off state ⁽²⁾	-0.5	6.5	V
Vo	Voltage range applied to any output in the high or low	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
lo	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾		259	°C/W	
T _{stg}	Storage temperature range	Storage temperature range			

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating" conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(2)

The value of V_{CC} is provided in the recommended operating conditions table. (3)

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

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Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
	Currente una la sec	Operating	1.65	5.5	V
V _{CC}	Supply voltage	Data retention only	1.5		v
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
		V_{CC} = 2.3 V to 2.7 V	1.7		
VIH	High-level input voltage	V_{CC} = 3 V to 3.6 V	2		V
		V_{CC} = 4.5 V to 5.5 V	$0.7 \times V_{CC}$		
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	
v		V_{CC} = 2.3 V to 2.7 V		0.7	V
V _{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	V
		V_{CC} = 4.5 V to 5.5 V		$0.3 \times V_{CC}$	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V _{CC}	V
		V _{CC} = 1.65 V		-4	
		$V_{CC} = 2.3 V$		-8	
I _{OH}	High-level output current	<u> </u>		-16	mA
		$V_{CC} = 3 V$		-24	
		$V_{CC} = 4.5 V$		-32	
		V _{CC} = 1.65 V		4	
		$V_{CC} = 2.3 V$		8	
I _{OL}	Low-level output current	<u> </u>		16	mA
		$V_{CC} = 3 V$		24	
		$V_{CC} = 4.5 V$		32	
		$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}, 2.5 \text{ V} \pm 0.2 \text{ V}$		20	
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V
		$V_{CC} = 5 V \pm 0.5 V$		10	
T _A	Operating free-air temperature	· · · · · · · · · · · · · · · · · · ·	-55	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN TYP ⁽¹⁾ M	AX UNI	T			
	$I_{OH} = -100 \ \mu A$	1.65 V to 5.5 V	V _{CC} – 0.1					
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2					
M	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9	V	V			
V _{OH}	$I_{OH} = -16 \text{ mA}$	2.1/	2.4	V				
	$I_{OH} = -24 \text{ mA}$	- 3 V	2.3					
	$I_{OH} = -32 \text{ mA}$	4.5 V	3.8					
	I _{OL} = 100 μA	1.65 V to 5.5 V		0.1				
	I _{OL} = 4 mA	1.65 V	(.45				
N	I _{OL} = 8 mA	2.3 V		0.3				
V _{OL}	I _{OL} = 16 mA	2.1/		0.4 V				
	I _{OL} = 24 mA	- 3 V	(.55				
	I _{OL} = 32 mA	4.5 V	(.55				
I _I All inputs	$V_1 = 5.5 \text{ V or GND}$	0 to 5.5 V		±5 μΑ				
l _{off}	$V_{I} \text{ or } V_{O} = 5.5 \text{ V}$	0		±10 μA	1			
I _{CC}	$V_{I} = 5.5 \text{ V or GND}, \qquad I_{O} = 0$	1.65 V to 5.5 V		10 μA				
ΔI _{CC}	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 5.5 V		500 μA				
Ci	$V_{I} = V_{CC} \text{ or } GND$	3.3 V	3.5	pF	:			

(1) All typical values are at $V_{CC} = 3.3$ V, $T_A = 25^{\circ}C$.

Switching Characteristics

over recommended operating free-air temperature range, C_L = 30 pF or 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		V _{CC} = 1.8 V = 0.15 V		V _{CC} = 2.5 V = 0.2 V		V _{CC} = 3.3 V = 0.3 V		= 5 V .5 V	UNIT
	(INPOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX]
t _{pd}	A, B, or C	Y	2.9	17.2	1.4	7.5	1.3	5.9	1	5.0	ns

Operating Characteristics

 $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	V _{CC} = 5 V TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 10 MHz	18	19	20	23	pF

SN74LVC1G11-EP

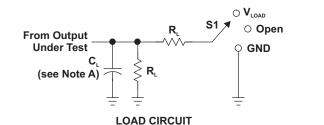


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v



PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	VLOAD
t_{PHZ}/t_{PZH}	GND

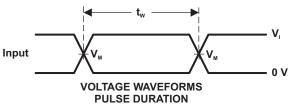
V_M

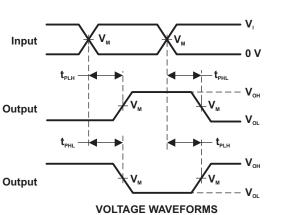
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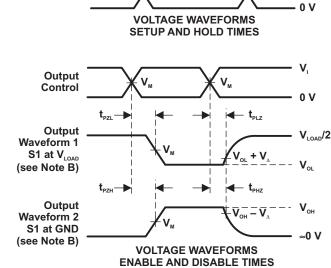
N	INPUTS			V	_	-	N
V _{cc}	V	t,/t,	V _M	VLOAD	C	R	V
1.8 V ± 0.15 V	V_{cc}	≤2 ns	V _{cc} /2	2 × V _{cc}	30 pF	1 k Ω	0.15 V
$2.5~V~\pm 0.2~V$	V_{cc}	≤2 ns	V _{cc} /2	2 × V _{cc}	30 pF	500 Ω	0.15 V
$3.3~V~\pm~0.3~V$	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
$5 V \pm 0.5 V$	V_{cc}	≤2.5 ns	V _{cc} /2	2 × V _{cc}	50 pF	500 Ω	0.3 V

Timing Input

Data Input







LOW- AND HIGH-LEVEL ENABLING

t

V_м

PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS

NOTES: A. C. includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_o = 50 Ω .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. $t_{\mbox{\tiny PLZ}}$ and $\dot{t}_{\mbox{\tiny PHZ}}$ are the same as $t_{\mbox{\tiny dis}}$
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. $t_{\mbox{\tiny PLH}}$ and $t_{\mbox{\tiny PHL}}$ are the same as $t_{\mbox{\tiny pd}}.$
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LVC1G11MDCKREP	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
V62/09621-01XE	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LVC1G11-EP :

• Catalog: SN74LVC1G11

• Automotive: SN74LVC1G11-Q1

PACKAGE OPTION ADDENDUM



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11-Feb-2012

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

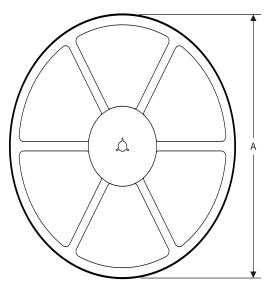
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

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TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G11MDCKREP	SC70	DCK	6	3000	180.0	8.4	2.25	2.4	1.22	4.0	8.0	Q3

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

27-Apr-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G11MDCKREP	SC70	DCK	6	3000	202.0	201.0	28.0

DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AB.



LAND PATTERN DATA



NOTES:

- A. All linear dimensions are in millimeters.B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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